S/N 10/602,323 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al. Examiner: Fernando L Toledo

al No.: 10/602,323 Group Art Unit: 2823

Filed: June 24, 2003 Docket: 1303.101US1
Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted, KIE Y. AHN ET AL.

By their Representatives, SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938

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Date 33 August 2004

By

David R. Cochra

Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 23 day of August, 2004.

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or the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 10/602,323 **Application Number** STATEMENT BY APPLICATE June 24, 2003 Filing Date (Use as many sheets as necessary) Ahn, Kie **First Named Inventor** AUG 2 5 2004 2823 **Group Art Unit** Toledo, Fernando **Examiner Name** Attorney Docket No: 1303.101US1 Sheet 1 of 5

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	10/602,323	
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	First Named Inventor	Ahn, Kie	
	Group Art Unit	2823	
	Examiner Name	Toledo, Fernando	
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	First Named Inventor	Ahn, Kie		
	Group Art Unit	2823		
	Examiner Name	Toledo, Fernando		
Sheet 5 of 5	Attorney Docket No: 1	1303.101US1		

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<u>PATENT</u>

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Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

COMMUNICATION CONCERNING RELATED APPLICATIONS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related applications in the above-identified patent application:

<u>Serial/Patent No.</u> 09/944,981	Filing Date August 30, 2001	Attorney Docket 1303.021US1	Title GATE OXIDES AND METHODS OF FORMING
09/945,535	August 30, 2001	1303.026US1	HIGHLY RELIABLE AMORPHOUS HIGH-K GATE OXIDE ZrO2
10/028,643	December 20, 2001	1303.030US1	LOW-TEMPERATURE GROWN HIGH QUALITY ULTRA-THIN CoTiO3 GATE DIELECTRICS
10/052,983 6,767,795	January 17, 2002	1303.031US1	HIGHLY RELIABLE AMORPHOUS HIGH-k GATE DIELECTRIC ZrOxNy
10/027,315	December 20, 2001	1303.033US1	LOW-TEMPERATURE GROWN HIGH-QUALITY ULTRA-THIN PRASEODYMIUM GATE DIELECTRICS
09/797,324	March 1, 2001	303.717US1	METHODS, SYSTEMS, AND APPARATUS FOR UNIFORM CHEMICAL-VAPOR DEPOSITIONS
10/099,194	March 13, 2002	1303.044US1	EVAPORATION OF Y-Si-O FILMS FOR MEDIUM-k DIELETRICS
10/081,439	February 20, 2002	1303.046US1	EVAPORATED LaAIO3 FILMS FOR GATE DIELECTRICS
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COMMUNICATION CONCERNING RELATED APPLICATIONS Serial Number: 10/602,323

Filing Date: June 24, 2003 Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

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			CIRCUITS
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10/163,481	June 5, 2002	1303.056US1	ATOMIC LAYER-DEPOSITED HfAIO3 FILMS FOR GATE DIELECTRICS
10/163,686	June 5, 2002	1303.059US1	Pr2O3-BASED La-oxide GATE DIELECTRICS
10/209,581	July 30, 2002	1303.061US1	ATOMIC LAYER DEPOSITED NANOLAMINATES OF HfO2/ZrO2 FILMS AS GATE DIELECTRICS
10/219,870	August 15, 2002	1303.069US1	LANTHANIDE DOPED TiOx DIELECTRIC FILMS BY PLASMA OXIDATION
. 10/219,878	August 15, 2002	1303.070US1	LANTHANIDE DOPED TiOx DIELECTRIC FILMS
10/229,903	August 28, 2002	1303.078US1	ATOMIC LAYER DEPOSITED HfSiON DIELECTRIC FILMS
10/233,309	August 29, 2002	1303.079US1	ATOMIC LAYER DEPOSITED LANTHANIDE DOPED TiOx DIELECTRIC FILMS
10/309,583	December 4, 2002	1303.082US1	ATOMIC LAYER DEPOSITED ZR- SN-TI-O FILMS USING TiI4
10/309,935	December 4, 2002	1303.083US1	ATOMIC LAYER DEPOSITED Zr-Sn-Ti-O FILMS
10/379,470	March 4, 2003	1303.090US1	ATOMIC LAYER DEPOSITED DIELECTRIC LAYERS

COMMUNICATION CONCERNING RELATED APPLICATIONS
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09/838,335 6,514,828	April 20, 2001		METHOD OF FABRICATING A HIGHLY RELIABLE GATE OXIDE
09/881,408	June 13, 2001		Dielectric layer forming method and devices formed therewith
09/908,767 6,534,420	July 18, 2001		METHODS FOR FORMING DIELECTRIC MATERIALS AND METHODS FOR FORMING SEMICONDUCTOR DEVICES
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10/789,042	February 27, 2004	1303.050US2	ATOMIC LAYER-DEPOSITED LaA1O3 FILMS FOR GATE DIELETRICS
10/789,044	February 27, 2004	1303.070US2	LANTHANIDE DOPED TiOx DIELECTRIC FILMS
	October 10, 2003		LANTHANIDE OXIDE/ ZIRCONIUM OXIDE ATOMIC LAYER DEPOSITED NANOLAMINATE GATE DIELECTRICS

COMMUNICATION CONCERNING RELATED APPLICATIONS
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Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

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10/052,983	January 17, 2002		HIGHLY RELIABLE AMORPHOUS HIGH K GATE DIELECTRIC ZROXNY
10/225,715	August 21, 2002		COMPOSITE DIELECTRIC FORMING METHODS AND COMPOSITE DIELECTRICS
10/352,507	January 27, 2003		ATOMIC LAYER DEPOSITION OF METAL OXYNITRIDE LAYERS AS GATE DIELECTRICS AND SEMICONDUCTOR DEVICE STRUCTURES UTILIZING METAL OXYNITRIDE LAYERS
10/863,953	June 9, 2004	1303.031US2	HIGHLY RELIABLE AMORPHOUS HIGH-k GATE DIELECTRIC ZrOxNy
09/779,959 6,495,436	February 9, 2001		IFORMATION OF METAL OXIDE GATE DIELECTRIC
09/838,335 6,514,828	April 20, 2001		METHOD OF FABRICATING A HIGHLY RELIABLE GATE OXIDE
09/881,408	June 13, 2001		Dielectric layer forming method and devices formed therewith
09/908,767 6,534,420	July 18, 2001		METHODS FOR FORMING DIELECTRIC MATERIALS AND METHODS FOR FORMING SEMICONDUCTOR DEVICES

COMMUNICATION CONCERNING RELATED APPLICATIONS

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 235 day of August, 2004.

Name 7

Signature